



AGENDA

THURSDAY, 17 OCTOBER

SkySong at ASU's Scottsdale Innovation Center
1365 North Scottsdale Road
Scottsdale, AZ 85257

SkySong Building 3 - Synergy I and II - 1365 N Scottsdale Rd

Time (MST)	SESSION	SPEAKER(S)
8:00 AM	Breakfast & Registration	
8:30 AM	Welcome & Introductions	<ul style="list-style-type: none"> • Kathy Hayashi, IEEE Region 6 Director • Tim Lee, 2024 IEEE-USA President-Elect
8:45 AM	Keynote: CHIPS Packaging Perspective	<ul style="list-style-type: none"> • Daniel Berger, Associate Director, National Advanced Packaging Manufacturing Program (NAPMP)
9:15 AM	The Future of Semiconductors in the U.S.	<ul style="list-style-type: none"> • Kathy Hayashi, IEEE Region 6 Director (moderator) • Rose Castanares, President, TSMC Arizona • Vincent (Woopoung) Kim, Ph.D., Corporate EVP, Head of Packaging, Samsung • Ravi Mahajan, Ph.D., Fellow, Intel
10:00 AM	The Future of Advanced Packaging in the U.S.	<ul style="list-style-type: none"> • David McCann, Senior Vice President, Chief of Staff, Business Units, Amkor Technology
10:30 AM	Networking Break	
10:45 AM	CHIPS Act and the Arizona Innovation Economy	<ul style="list-style-type: none"> • Chris Bailey, Ph.D., Professor, Electrical Engineering, Arizona State University (moderator) • Jason Conrad, Chief Operating Officer, Southwest Advanced Prototyping (SWAP) Hub, ASU Knowledge Enterprise • Sean Fogarty, VP of International Business Development, Greater Phoenix Economic Council • Scott Hayes, Technical Director, NXP Semiconductors • Tim Olson, Founder, CEO, and Director, Deca • Curtis Zwenger, Treasurer, IMAPS/Amkor Technology

Breakout Sessions - SkySong Building 1 - Rooms 301 & 349 - 1475 N Scottsdale Rd

11:45 AM	BREAKOUT SESSION	PANEL DISCUSSIONS
Building 1 Room 301	1) CHIPS Workforce Development	<ul style="list-style-type: none"> • Falan Yinug, Director of Economic Strategy, Qualcomm (moderator) • Stewart Barber, Senior Director of Government Affairs, Synopsys • Jennifer Fong, Director, Continuing Education Product and Business Development, IEEE Educational Activities • Taylor Roundtree, Associate Partner, McKinsey & Company • Rick Vaughn, Ph.D., Faculty Chair, STEM, Rio Salado College
Building 1 Room 349	2) EDA and Packaging	<ul style="list-style-type: none"> • Heather Monigan, Chair, IEEE Phoenix Section/CSS Partnership (moderator) • Antonio de la Serna, Principal Director, Strategic Technology, Siemens EDA • Darin Heckendorn, Account Technical Director for Aerospace and Defense, Cadence Design Systems



AGENDA

SkySong Building 3 - Synergy I and II - 1365 N Scottsdale Rd

Time (MST)	SESSION	SPEAKER(S)
12:30 PM	Networking Lunch	
1:15 PM	Fireside Chat with the Arizona Commerce Authority	<ul style="list-style-type: none"> • Sandra Watson, President and CEO, Arizona Commerce Authority • Erik Heilman, Director of Government Relations, IEEE-USA
2:15 PM	DARPA and CHIPS	<ul style="list-style-type: none"> • Michael Holmes, Managing Director, Next Generation Microelectronics Manufacturing (NGMM), DARPA
3:00 PM	Networking Break	

Breakout Sessions - SkySong Building 1 - Rooms 301 & 349 - 1475 N Scottsdale Rd

3:30 PM	BREAKOUT SESSIONS	PANEL DISCUSSIONS
Building 1 Room 301	1) CHIPS Opportunities and Challenges	<ul style="list-style-type: none"> • Matt Francis, Ph.D., IEEE Region 5 Director and Founder and President/ CEO, Ozark IC (moderator) • Jyotika Athavale, President, IEEE Computer Society/ Synopsys • Rafi Islam, Ph.D., CEO and CTO, Cactus Materials • Andrea Wallace, Electro Mechanical Engineer, RTX
Building 1 Room 349	2) What's Next for CHIPS in Washington	<ul style="list-style-type: none"> • Erik Hadland, Ph.D., Director, Technology Policy, Semiconductor Industry Association • Russell Harrison, Managing Director, IEEE-USA

SkySong Building 3 - Synergy I and II - 1365 N Scottsdale Rd

Time (MST)	SESSION	SPEAKER(S)
4:30 PM	Closing Remarks and Next Steps	<ul style="list-style-type: none"> • Kathy Hayashi, IEEE Region 6 Director • Tim Lee, 2024 IEEE-USA President-Elect
5:00 PM	Wrap-Up and Adjourn	

THANKS TO OUR SPONSORS

